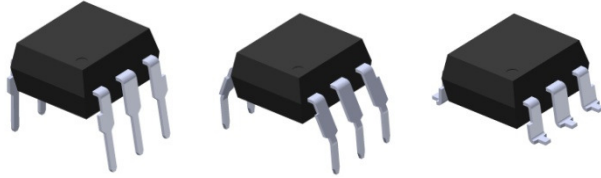
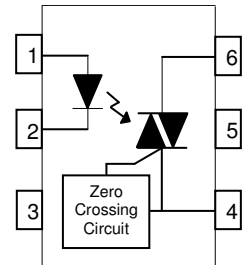


### DATASHEET

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER



Schematic



Pin Configuration

1. Anode
2. Cathode
3. No Connection
4. Terminal
5. Substrate  
(do not connect)
6. Terminal

#### Features:

- Peak breakdown voltage
  - 250V: MOC303X
  - 400V: MOC304X
  - 600V: MOC306X
  - 800V: MOC308X
- High isolation voltage between input and output (Viso=5000 V rms)
- Zero voltage crossing
- Pb free and RoHS compliant.
- UL approved (No. E214129)
- VDE approved (No.132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CSA approved

#### Description

The MOC303X, MOC304X, MOC306X and MOC308X series of devices each consist of a GaAs infrared emitting diode optically coupled to a monolithic silicon zero voltage crossing photo triac.

They are designed for use with a discrete power triac in the interface of logic systems to equipment powered from 110 to 380 VAC lines, such as solid-state relays, industrial controls, motors, solenoids and consumer appliances.

#### Applications

- Solenoid/valve controls
- Light controls
- Static power switch
- AC motor drivers
- E.M. contactors
- Temperature controls
- AC Motor starters

### DATASHEET

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

#### Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Rating	Unit	
Input	Forward current	$I_F$	60	mA	
	Reverse voltage	$V_R$	6	V	
	Power dissipation	$P_D$	100	mW	
	Derating factor (above $T_a = 85^\circ\text{C}$ )		3.8	mW / °C	
Output			MOC303X	250	
	Off-state Output Terminal Voltage	$V_{DRM}$	MOC304X	400	V
			MOC306X	600	
			MOC308X	800	
			Peak Repetitive Surge Current (pw=1ms, 120pps)	$I_{TSM}$	
	On-State RMS Current	$I_{T(RMS)}$	100	mA	
	Power dissipation	$P_C$	300	mW	
	Derating factor (above $T_a = 85^\circ\text{C}$ )		7.6	mW/°C	
Total power dissipation	$P_{TOT}$	330	mW		
Isolation voltage <sup>*1</sup>	$V_{ISO}$	5000	Vrms		
Operating temperature	$T_{OPR}$	-55 to 100	°C		
Storage temperature	$T_{STG}$	-55 to 125	°C		
Soldering Temperature <sup>*2</sup>	$T_{SOL}$	260	°C		

Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2&3 are shorted together, and pins 4, 5 & 6 are shorted together.

\*2 For 10 seconds

### DATASHEET

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

#### Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

##### Input

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Forward Voltage	$V_F$	-	-	1.5	V	$I_F = 30\text{mA}$
Reverse Leakage current	$I_R$	-	-	10	$\mu\text{A}$	$V_R = 6\text{V}$

##### Output

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Peak Blocking Current	$I_{\text{DRM1}}$	-	-	100 500	nA	$V_{\text{DRM}} = \text{Rated } V_{\text{DRM}}$ $I_F = 0\text{mA}$
Peak On-state Voltage	$V_{\text{TM}}$	-	-	3	V	$I_{\text{TM}} = 100\text{mA peak}$ , $I_F = \text{Rated } I_{\text{FT}}$
Critical Rate of Rise off-state Voltage	$dv/dt$	1000 600	-	-	V/ $\mu\text{s}$	$V_{\text{PEAK}} = \text{Rated } V_{\text{DRM}}$ , $I_F = 0$ (Fig. 10)
Inhibit Voltage (MT1-MT2 voltage above which device will not trigger)	$V_{\text{INH}}$	-	-	20	V	$I_F = \text{Rated } I_{\text{FT}}$
Leakage in Inhibited State	$I_{\text{DRM2}}$	-	-	500	$\mu\text{A}$	$I_F = \text{Rated } I_{\text{FT}}$ , $V_{\text{DRM}} = \text{Rated } V_{\text{DRM}}$ , off state

##### Transfer Characteristics

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
LED Trigger Current	$I_{\text{FT}}$	-	-	15 10 5	mA	Main terminal Voltage=3V
Holding Current	$I_H$	-	280	-	$\mu\text{A}$	

\* Typical values at  $T_a = 25^\circ\text{C}$

### DATASHEET

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

### Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

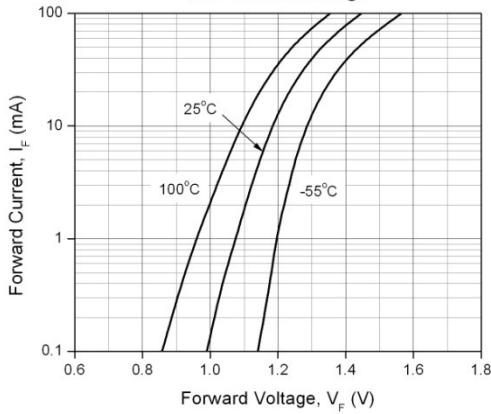


Figure 2. On-State Characteristics

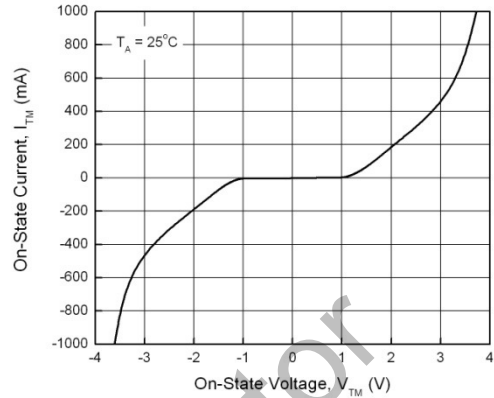


Figure 3. Holding Current vs. Ambient Temperature

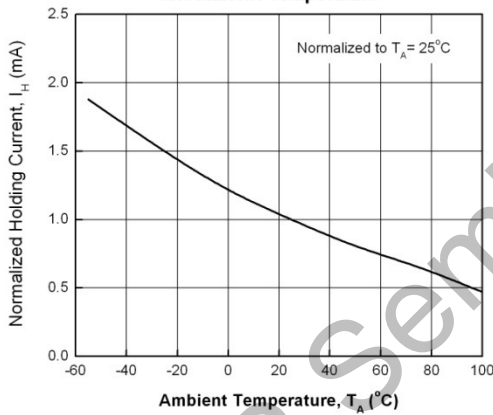


Figure 4. LED Current Required to Trigger vs. LED Pulse Width

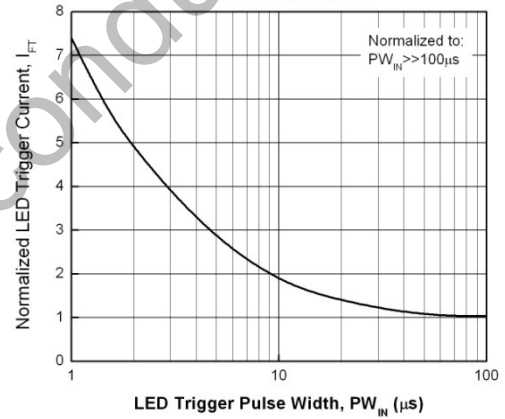


Figure 5. Leakage Current vs. Ambient Temperature

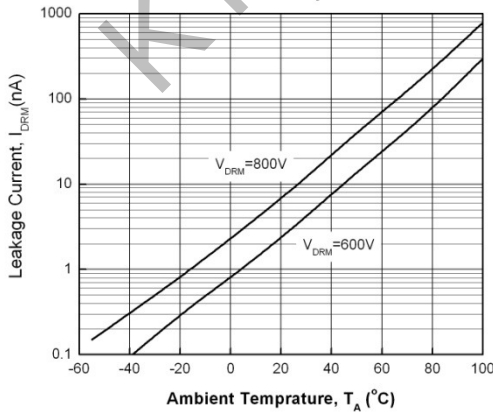
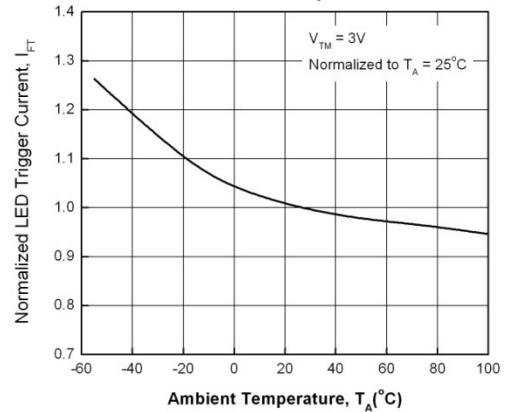


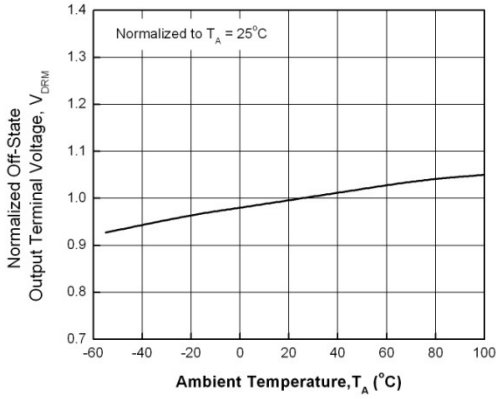
Figure 6. LED Trigger Current vs. Ambient Temperature



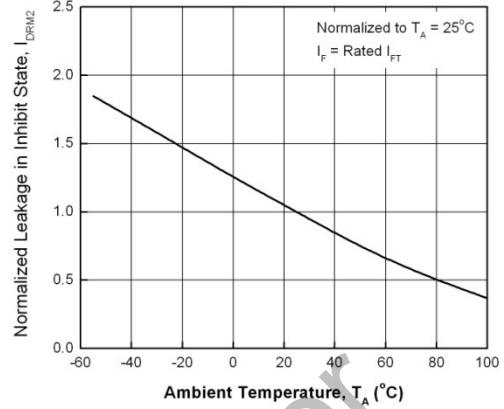
### DATASHEET

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

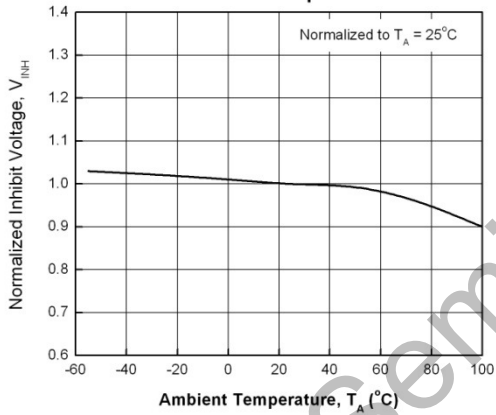
**Figure 7. Off-State Output Terminal Voltage vs. Ambient Temperature**



**Figure 8. Leakage in Inhibit State vs. Ambient Temperature**



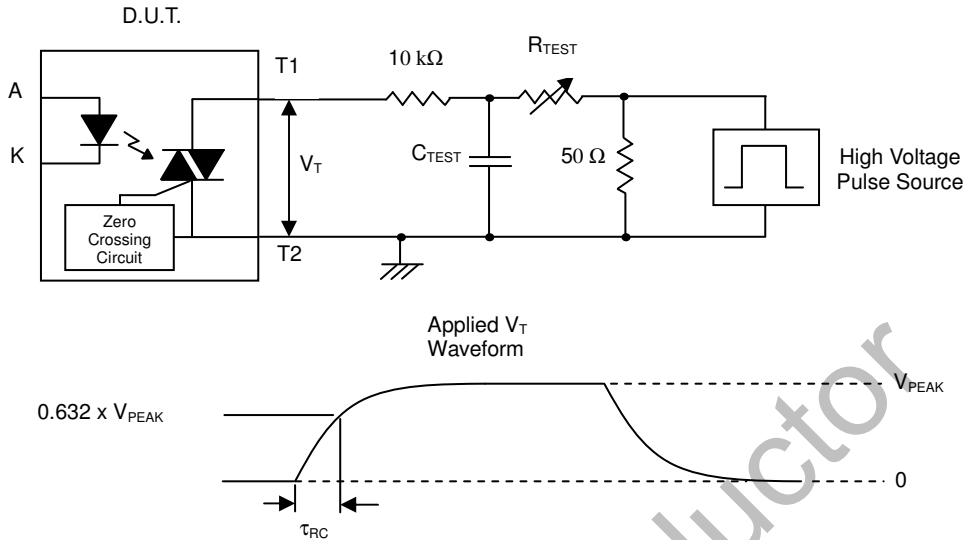
**Figure 9. Inhibit Voltage vs. Ambient Temperature**



### DATASHEET

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

Figure 10. Static dv/dt Test Circuit & Waveform



#### Measurement Method

The high voltage pulse is set to the required  $V_{PEAK}$  value and applied to the D.U.T. output side through the RC circuit above. LED current is not applied. The waveform  $V_T$  is monitored using a x100 scope probe. By varying  $R_{TEST}$ , the  $dv/dt$  (slope) is increased, until the D.U.T. is observed to trigger (waveform collapses). The  $dv/dt$  is then decreased until the D.U.T. stops triggering. At this point,  $\tau_{RC}$  is recorded and the  $dv/dt$  calculated.

$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

For example,  $V_{PEAK} = 600V$  for MOC306X series. The  $dv/dt$  value is calculated as follows:

$$dv/dt = \frac{0.63 \times 600}{\tau_{RC}} = \frac{378}{\tau_{RC}}$$

**DATASHEETL****6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER**

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**Order Information****Part Number**

**MOC303XY(Z)-V**  
or **MOC304XY(Z)-V**  
or **MOC306XY(Z)-V**  
or **MOC308XY(Z)-V**

Note

X = Part No. (1, 2 or 3)

Y = Lead form option (S, S1, M or none)

Z = Tape and reel option (TA, TB or none).

V = VDE safety approved option

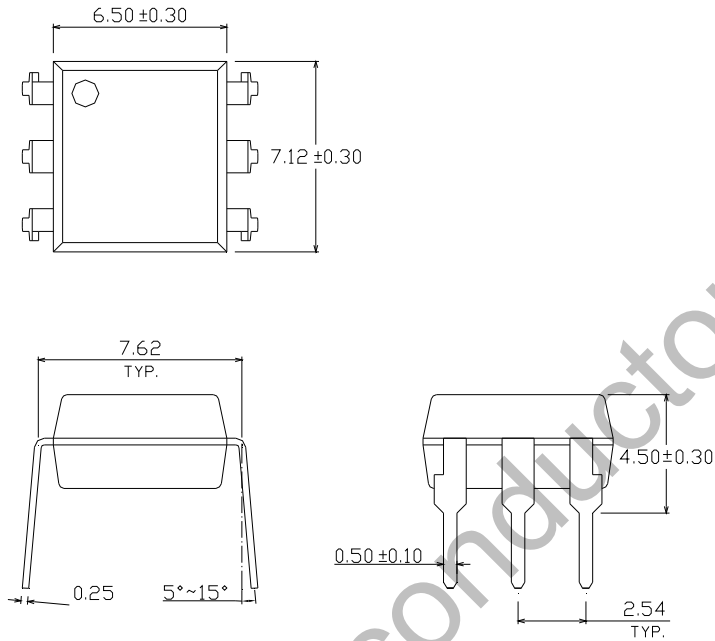
Option	Description	Packing quantity
None	Standard DIP-6	65 units per tube
M	Wide lead bend (0.4 inch spacing)	65 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

### DATASHEETL

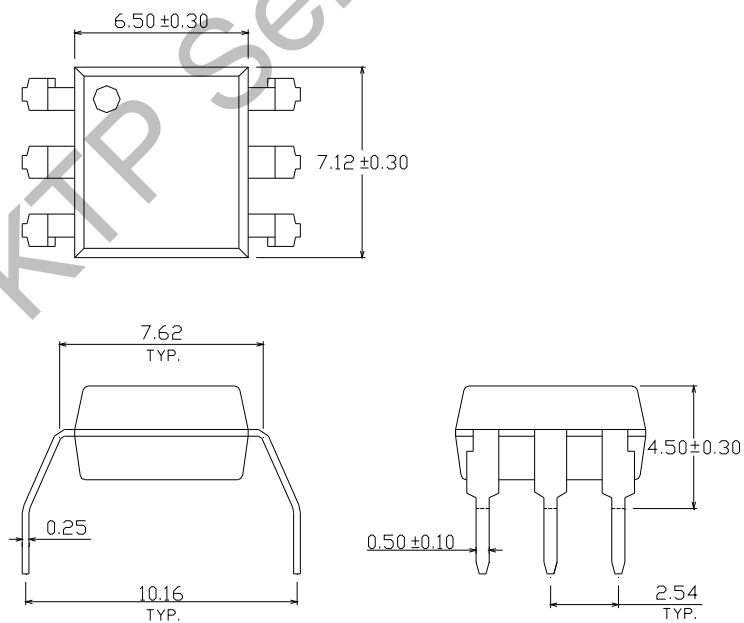
### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

#### Package Dimension (Dimensions in mm)

##### Standard DIP Type



##### Option M Type

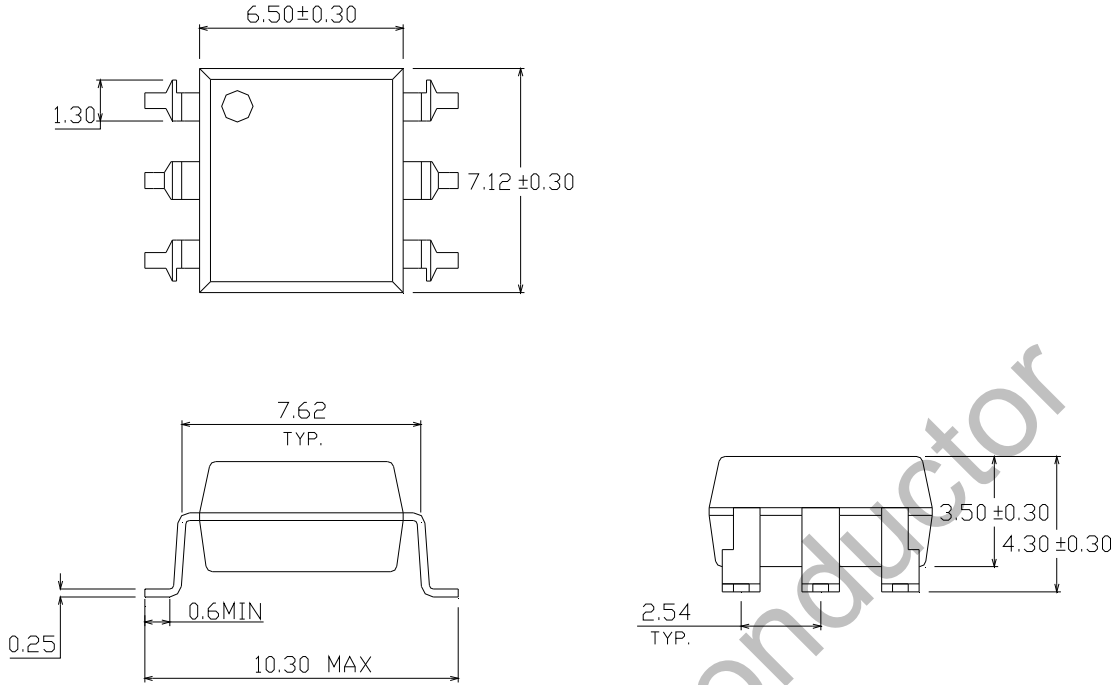




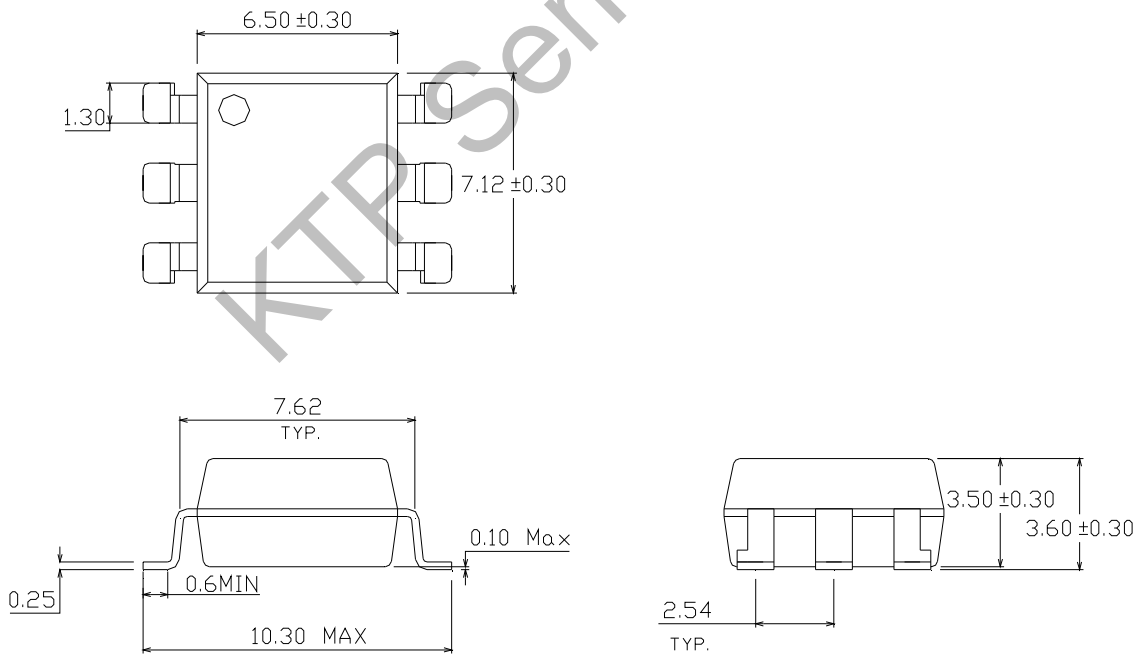
### DATASHEETL

### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

#### Option S Type



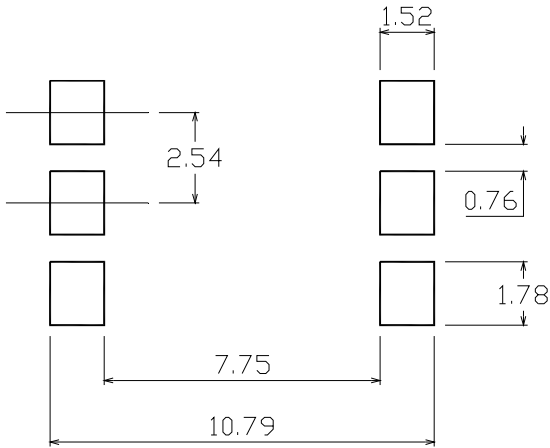
#### Option S1 Type



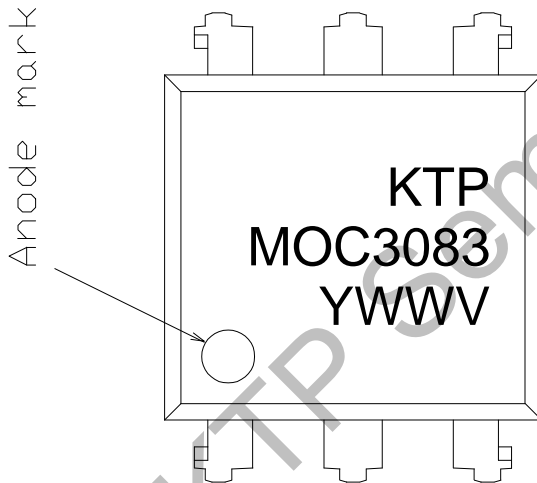
### DATASHEETL

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

##### Recommended pad layout for surface mount leadform



##### Device Marking



##### Notes

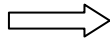
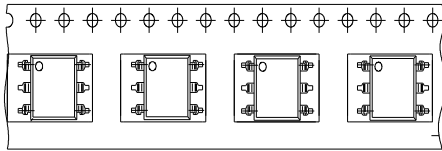
- KTP denotes Brand LOGO
- 3083 denotes Device Number
- Y denotes 1 digit Year code
- WW denotes 2 digit Week code
- V denotes VDE option

### DATASHEETL

### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

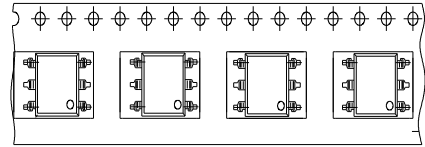
#### Tape & Reel Packing Specifications

**Option TA**



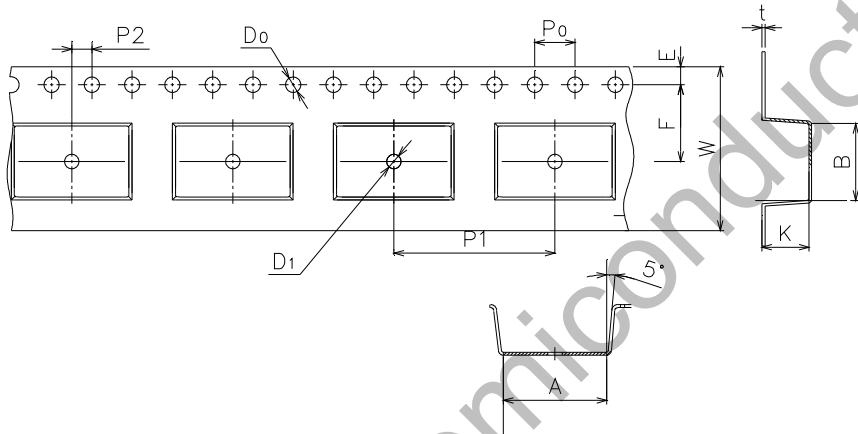
Direction of feed from reel

**Option TB**



Direction of feed from reel

#### Tape dimensions



Dimension No.	A	B	Do	D1	E	F
Dimension (mm)	10.4±0.1	7.5±0.1	1.5±0.1	1.5+0.1/-0	1.75±0.1	7.5±0.1

Dimension No.	Po	P1	P2	t	W	K
Dimension (mm)	4.0±0.15	12±0.1	2.0±0.1	0.35±0.03	16.0±0.2	4.5±0.1

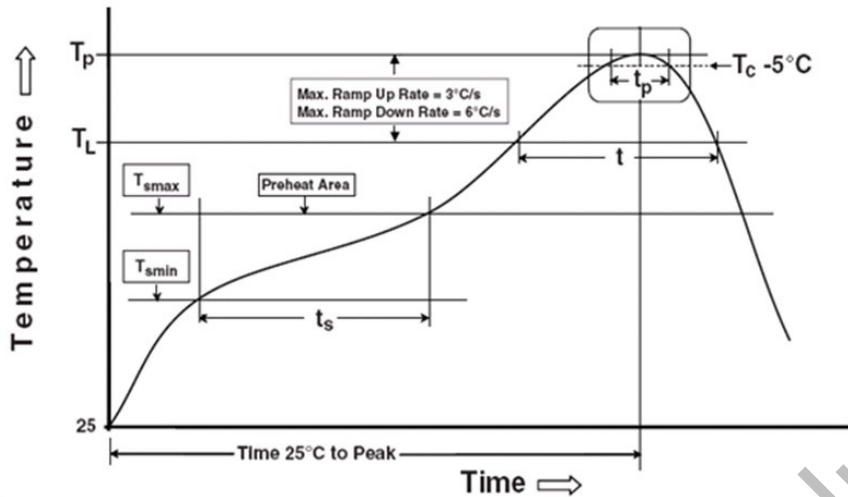
### DATASHEET

#### 6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

### Precautions for Use

#### 1. Soldering Condition

##### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_p$ )	60-100 sec
Peak Temperature ( $T_p$ )	260 °C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6 °C /second max.
Time 25 °C to peak temperature	8 minutes max.
Reflow times	3 times.

**DATASHEETL****6 PIN DIP ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER**

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**DISCLAIMER**

1. Above specification may be changed without notice. KTP will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. KTP assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.

KTP Semiconductor